


Full Material Declaration for attached parts list

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	<p>Diotec Semiconductor AG DUNS number: 330866844 -, Kreuzmattenstr. 4, Heitersheim, B.-W., 79423, Germany Declarations authorised by Udo Steinebrunner, Product Manager, -</p>
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Declaration effective from: 02 January 2015 [Approved: 14 August 2023 13:25 GMT]

Individual materials in the part			Individual substances in each material		
Use/Location	Material Group	Max mass %	Substance	CAS Number	Max mass %
Chip (die)	Other inorganic materials	0.22%	ALUMINIUM	7429-90-5	0.1%
			Nickel REACH Article 67 Exemption	7440-02-0	0.4%
			Silver	7440-22-4	28.6%
			Silicon	7440-21-3	70.9%
			Aluminum oxide (Al ₂ O ₃)	1344-28-1	2%
			Sodium oxide (Na ₂ O)	1313-59-3	3%
Encapsulation	Glass	26.1%	Lithium oxide (Li ₂ O)	12057-24-8	4%
			Rutile (TiO ₂)	1317-80-2	4%
			ZINCITE (MINERAL)	1314-13-2	4%
			Potassium oxide (K ₂ O)	12136-45-7	7.5%
			Boron oxide (B ₂ O ₃)	1303-86-2	20%
Leadfinish	Tin plating	0.15%	Silicon Dioxide	7631-86-9	55.5%
			Tin	7440-31-5	100%
Leadframe	Copper (e.g. copper amounts in cable harnesses)	73.53%	Copper	7440-50-8	24%
			Iron	7439-89-6	34%
			Nickel REACH Article 67 Exemption	7440-02-0	42%

Attached parts list

Part number	Part name
MicroMelf-Glass_PbF	Diode SMD